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AMENDMENTS TO THE CLAIMS

Claims 1-17 (Cancelled)

18. (Currently Amended) An apparatus, comprising:
a heat sink comprising a thermoelectric (TEC) module having a polarity, the
polarity capable of being adjusted to direct or redirect heat in one or more
directions to melt or un-melt a thermal interface material (TIM); and
the thermal interface material (TIM) coupled with the heat sink, the TIM receiving
the heat in the heat sink upon changing of the polarity to melt the TIM up
to an acceptable melt level to be applied to or removed from the heat sink,
the TIM including a thermal conductive material to fill a thermal gap to
dissipate the heat away from a integrated circuit (IC).
19. (Currently Amended) The apparatus of claim 18, wherein the TIM is applied to or
removed from one or more of a base of the heat sink, a the thermal gap between
the heat sink, and a heat source.
20. (Previously Presented) The apparatus of claim 18, wherein the TIM is applied via
an application device, the application device including one or more of an epoxy
dispenser machine and a vacuum suction cup.
21. (Previously Presented) The apparatus of claim 18, wherein the adjusting of the
polarity comprises reversing of the polarity.
22. (Previously Presented) The apparatus of claim 21, wherein the adjusting of the
polarity is performed via one or more of reversing terminals of the TEC module,
and adjusting a power source.
23. (Currently Amended) A system, comprising:
a storage medium;

a integrated circuit (IC) device coupled with the storage medium;
a heat sink coupled with the IC device, the heat sink comprising a thermoelectric (TEC) module having a polarity, the polarity capable of being adjusted to direct or redirect heat in one or more directions to melt or un-melt a thermal interface material (TIM); and
the thermal interface material (TIM) coupled with the heat sink and the IC device, the TIM receiving the heat in the heat sink upon changing of the polarity to melt the TIM up to an acceptable melt level to be applied to or removed from the heat sink, the TIM including a thermal conductive material to fill a thermal gap to dissipate the heat away from the IC.

24. (Currently Amended) The system of claim 23, wherein the TIM is applied to or removed from one or more of a base of the heat sink, ~~a~~ the thermal gap between the heat sink, and a heat source.
25. (Previously Presented) The system of claim 23, wherein the TIM is applied via an application device, the application device comprising one or more of an epoxy dispenser machine and a vacuum suction cup.
26. (Original) The system of claim 23, wherein the changing of the polarity comprises reversing of the polarity.
27. (Previously Presented) The system of claim 26, wherein the reversing of the polarity is performed via one or more of reversing terminals of the TEC module, a device to change the polarity of the TEC module, and adjusting a power source.
28. (Previously Presented) The system of claim 23, wherein the IC device comprises one or more of a microprocessor, a microcontroller, a graphics processor, a digital signal processor (DSP), a complex instruction set computing (CISC) processor, a

reduced instruction set computing (RISC) processor, and a very long instruction word (VLIW) processor.